

Dual N-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω) MAX.	I _D (A)	Q _g (TYP.)		
30	0.540 at V _{GS} = 4.5 V	0.5			
	0.600 at V _{GS} = 2.5 V	0.2	0.72 nC		
	0.700 at V _{GS} = 1.8 V	0.2	0.72110		
	1.100 at V _{GS} = 1.5 V	0.05			

SC-89 Dual (6 leads) S₂ G₂ 4 D₁ 5 Top View

Marking Code: B Ordering Information:

Si1036X-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

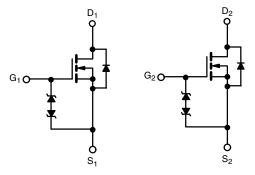
- TrenchFET® Power MOSFET
- 100 % R_a tested
- Gate-source ESD protected: 1000 V
- Material categorization:
 For definitions of compliance please see www.vishay.com/doc?99912



ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

- Load switch
- · High speed switching
- DC/DC converters / boost converters
- · For smart phones, tablet PCs and mobile computing



N-Channel MOSFET

N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V _{DS}	30	V	
Gate-Source Voltage		V_{GS}	± 8		
Continuous Drain Courant (T. 150 °C) 3	T _A = 25 °C	- I _D	0.61 ^{a,b}		
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 70 °C		0.49 ^{a,b}	Α	
Pulsed Drain Current (t = 100 μs)		I _{DM}	2		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	0.18 ^{a,b}	Α	
Maximum Dawar Dissipation 8	T _A = 25 °C	D	0.22 ^{a,b}	_ w	
Maximum Power Dissipation ^a	T _A = 70 °C	P _D	0.14 ^{a,b}		
Operating Junction and Storage Temperature Ra	ange	T _J , T _{stg}	-55 to 150	°C	

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient ^b	t ≤ 5 s	R _{thJA}	470	565	°C/W	
Waximum Junction-to-Ambient	Steady State		560	675		

Notes

a. Surface mounted on 1" x 1" FR4 board.

b. t = 5 s.



www.vishay.com

Vishay Siliconix

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static				•		I.	
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30	-	-	V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	1 050 A	-	29	-	mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA	-	-1.8	-	mv/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.4	-	1	V	
Cata Sauraa Laakaga	Lead	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$	-	-	± 30	μΑ	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$	-	-	± 1		
Zero Gate Voltage Drain Current	l	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 85 ^{\circ}\text{C}$	-	-	3		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	2	-	-	Α	
		$V_{GS} = 4.5 \text{ V}, I_D = 0.5 \text{ A}$	-	0.450	0.540		
Dunin Course On Chata Basistana 3	D	$V_{GS} = 2.5 \text{ V}, I_D = 0.2 \text{ A}$	-	0.500	0.600	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 1.8 \text{ V}, I_D = 0.2 \text{ A}$	-	0.560	0.700		
		$V_{GS} = 1.5 \text{ V}, I_D = 0.05 \text{ A}$	-	0.647	1.100		
Forward Transconductance	9 _{fs}	$V_{DS} = 15 \text{ V}, I_D = 0.5 \text{ A}$	-	7.5	-	S	
Dynamic ^b							
Input Capacitance	C _{iss}		-	36	-		
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	9	-	pF	
Reverse Transfer Capacitance	C _{rss}		-	5	-		
Total Cata Charge	0	$V_{DS} = 15 \text{ V}, V_{GS} = 8 \text{ V}, I_D = 0.5 \text{ A}$	-	1.2	2		
Total Gate Charge Q _g			-	0.72	1.2	nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 0.5 \text{ A}$	-	0.1	-	nC	
Gate-Drain Charge	Q _{gd}		-	0.16	-		
Gate Resistance	R _g	f = 1 MHz	2.4	12.2	24.4	Ω	
Turn-On Delay Time	t _{d(on)}		-	6	15		
Rise Time	t _r	$V_{DD} = 15 \text{ V}, R_{L} = 37.5 \Omega$	-	13	24	ns	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 0.4 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$	-	20	30		
Fall Time	t _f		-	11	20		
Drain-Source Body Diode Characterist	ics						
Pulse Diode Forward Current ^a	I _{SM}		-	-	2	Α	
Body Diode Voltage	V _{SD}	I _S = 0.5 A	-	0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}		-	8	15	ns	
Body Diode Reverse Recovery Charge	Body Diode Reverse Recovery Charge Q		-	2	4	nC	
Reverse Recovery Fall Time	t _a	I _F = 0.4 A, dl/dt = 100 A/μs		4	-	ns	
Reverse Recovery Rise Time	t _b			4	-		

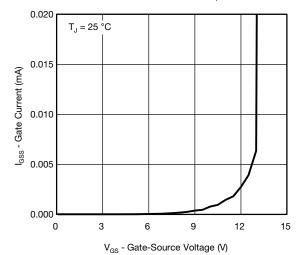
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

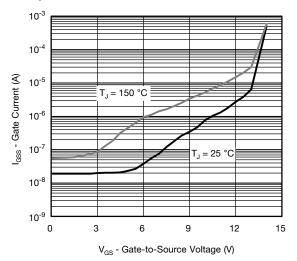
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



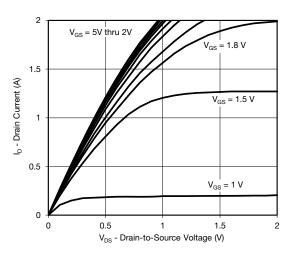
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



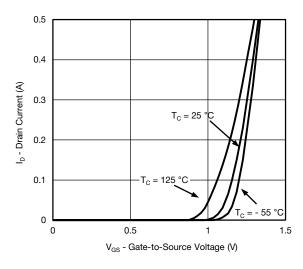
Gate Current vs. Gate-Source Voltage



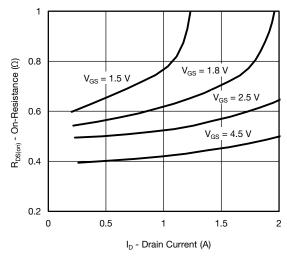
Gate Current vs. Gate-Source Voltage

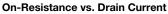


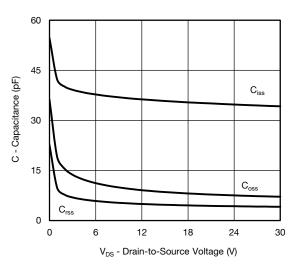
Output Characteristics



Transfer Characteristics



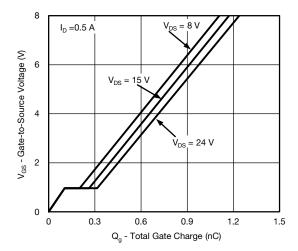




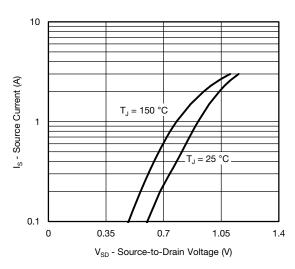
Capacitance



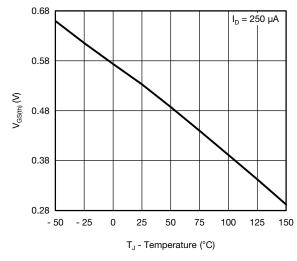
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



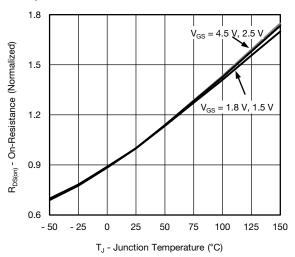
Gate Charge



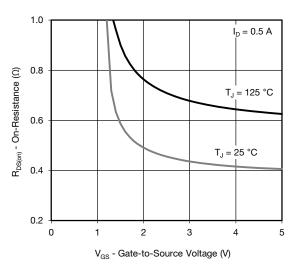
Soure-Drain Diode Forward Voltage



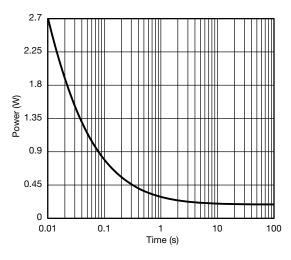
Threshold Voltage



On-Resistance vs. Junction Temperature



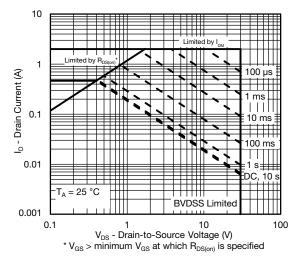
On-Resistance vs. Gate-to-Source Voltage

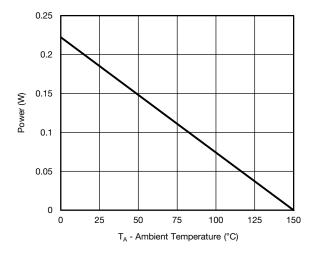


Single Pulse Power, Junction-to-Ambient



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

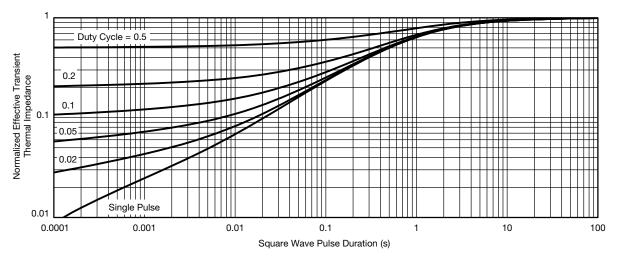




Safe Operating Area, Junction-to-Ambient

Power Derating, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max.)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

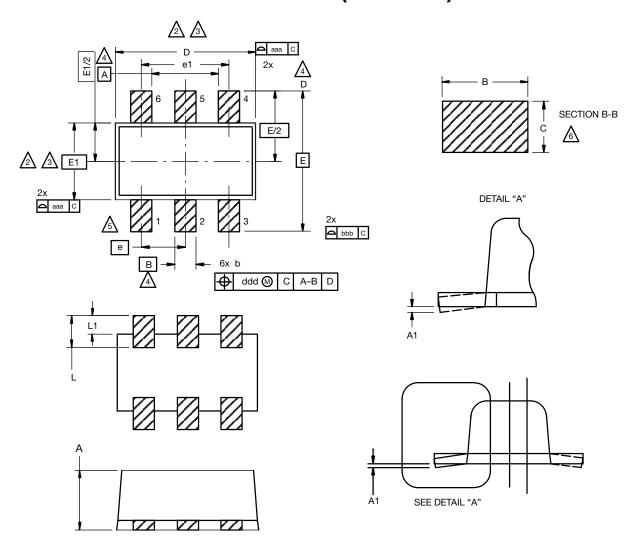


Normalized Thermal Transient Impedance, Junction-to-Ambient

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg262932.



SC-89 6-Leads (SOT-563F)



Notes

1. Dimensions in millimeters.

Dimension D does not include mold flash, protrusions or gate burrs. Mold flush, protrusions or gate burrs shall not exceed 0.15 mm per dimension E1 does not include interlead flash or protrusion, interlead flash or protrusion shall not exceed 0.15 mm per side.

Dimensions D and E1 are determined at the outmost extremes of the plastic body exclusive of mold flash, the bar burrs, gate burrs and interlead flash, but including any mismatch between the top and the bottom of the plastic body.

ADatums A, B and D to be determined 0.10 mm from the lead tip.

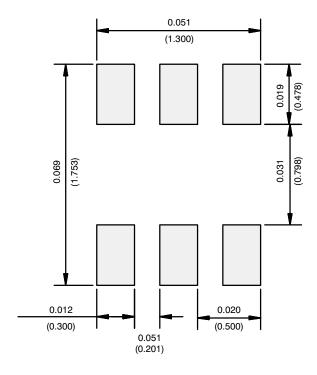
A Terminal numbers are shown for reference only.

These dimensions apply to the flat section of the lead between 0.08 mm and 0.15 mm from the lead tip.

DIM.	MILLIMETERS					
DIW.	MIN.	NOM.	MAX.			
Α	0.56	0.58	0.60			
A1	0	0.02	0.10			
b	0.15	0.22	0.30			
С	0.10	0.14	0.18			
D	1.50	1.60	1.70			
E	1.50	1.60	1.70			
E1	1.15	1.20	1.25			
е	0.45	0.50	0.55			
e1	0.95	1.00	1.05			
L	0.25	0.35	0.50			
L1	0.10	0.20	0.30			
C14-0439-Rev. C, 11-Aug-14 DWG: 5880						



RECOMMENDED MINIMUM PADS FOR SC-89: 6-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

Return to Index

APPLICATION NOTE



Legal Disclaimer Notice

Vishay

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Hyperlinks included in this datasheet may direct users to third-party websites. These links are provided as a convenience and for informational purposes only. Inclusion of these hyperlinks does not constitute an endorsement or an approval by Vishay of any of the products, services or opinions of the corporation, organization or individual associated with the third-party website. Vishay disclaims any and all liability and bears no responsibility for the accuracy, legality or content of the third-party website or for that of subsequent links.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.